



(2,00mm) .0787"

FCT, EMT SERIES

# FLEXCARD™ TERMINAL & SOCKET STRIPS

Mates with:  
EMT

## SPECIFICATIONS

For complete specifications and recommended PCB layouts see [www.samtec.com?FCT](http://www.samtec.com?FCT)

**Insulator Material:**  
Black Liquid Crystal Polymer



**Terminal Material:**  
Phosphor Bronze

**Current Rating:**  
3A @ 80°C ambient

**Operating Temp Range:**  
-55°C to +105°C with Tin;  
-55°C to +125°C with Gold

**Plating:**  
Sn or Au over 50µ" (1,27µm) Ni

**RoHS Compliant:**  
Yes

### Processing:

**Max Processing Temp:**  
230°C for 60 seconds or  
260°C for 20 seconds 3x  
with Matte Sn plating  
**Lead-Free Solderable:**  
Wave, or reflow with  
Matte Sn plating

**Note:** Some lengths, styles and options are non-standard, non-returnable.

**FCT**

**1**

**NO. PINS PER ROW**

**LEAD STYLE**

**PLATING OPTION**

**D**

**CARD SLOT**

**TAIL OPTION**

**SL**

  

**20, 30 & 40**  
(Call Samtec for other sizes)

Specify LEAD STYLE from chart

**-F**  
= Gold flash on post, Matte Tin on tail  
  
**-L**  
= 10µ" (0,25µm) Gold on post, Matte Tin on tail  
  
**-S**  
= 30µ" (0,76µm) Gold on post, Matte Tin on tail

**-01**  
= Accepts (0,80mm) .031" thick card  
  
**-RA**  
= Right Angle  
(Leave blank for vertical version. Style -02 only)

  

LEAD STYLE	Y	CARD-TO-BOARD SPACE (X)
-02	(6,35) .250	(2,60) .1025
-03	(9,53) .375	(5,78) .2275

  

## SPECIFICATIONS

For complete specifications and recommended PCB layouts see [www.samtec.com?EMT](http://www.samtec.com?EMT)

**Insulator Material:**  
Black LCP



**Contact Material:**  
BeCu

**Current Rating:**  
3A @ 80°C ambient

**Operating Temp Range:**  
-55°C to +125°C

**Plating:** Sn or Au over 50µ" (1,27µm) Ni

**Contact Resistance:**  
10 mΩ max

**Insertion Depth:** (3,05mm) .120" to (3,30mm) .130"

**Insertion Force:**  
-01=1.5oz (0,44N) average  
-51=2.5oz (0,70N) average

**Withdrawal Force:**  
-01=1.1oz (0,31N) average  
-51=1.5oz (0,44N) average

**Max Processing Temp:**  
230°C for 60 seconds or  
260°C for 20 seconds 3x  
with Matte Sn plating

**Lead-Free Solderable:**  
Yes, with Matte Sn plating

**SMT Lead Coplanarity:**  
(0,10mm) .004" max (20)  
(0,15mm) .006" max (30-40)

**RoHS Compliant:** Yes

**EMT**

**1**

**NO. PINS PER ROW**

**CARD THICKNESS**

**PLATING OPTION**

**D**

  

**20, 30, 40**  
(Call Samtec for other sizes)

**-01**  
= (0,80mm) .031" thick board (Low Insertion Force)  
  
**-51**  
= (0,80mm) .031" thick board (Standard Insertion Force)

**-L**  
= 10µ" (0,25µm) Gold on contact, Matte on tail  
  
**-S**  
= 30µ" (0,76µm) Gold on contact, Matte Tin on tail

  

*Due to technical progress, all designs, specifications and components are subject to change without notice.*

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